Aldehyde Free Bio-adhesive Prepared from Soy Protein Isolate and Depolymerized Lignin

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Research Background

- Concerns over formaldehyde release from aldehyde-based adhesives
- Renewable and degradable biobased adhesive from biomass
- Utilizing abundant lignin residue from forest product industry
- Challenges being improvements of dispersion, water resistance, and bonding strength



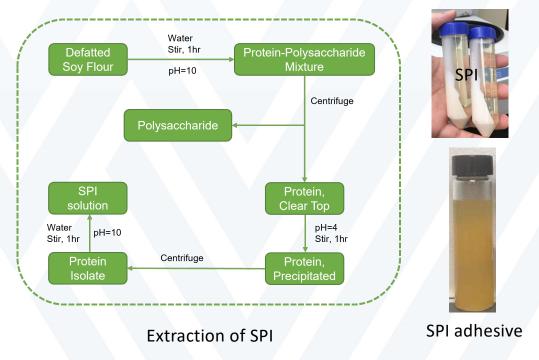






Soy Protein Isolate and Soy Protein Adhesive

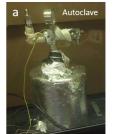
- Defatted soy flour has ~51% soy protein
- Soy protein isolate (SPI) can be extracted using the pictured process
- SPI can be further dissolved to prepare
 SPI adhesive
- The adhesive system is water-based and formaldehyde-free





Lignin Fragments and Soy Protein-Lignin Adhesive

- Commercial kraft lignin was used to produce partially degraded lignin and resulted bio-adhesive.
- Mild base-catalyzed depolymerization at 140-200 °C were adopted ^[1].
- Lignin derived from biomass was also proven in lab as a similar candidate to prepare bio-adhesive





Autoclave reactor



SPI, Lignin fragment, Bio-adhesive



Lignin extraction for 2 hr at 140 °C



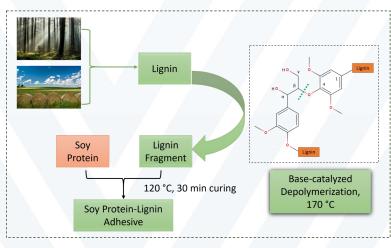
Lignin extraction for 18 hr at 140 °C



Bio-adhesive with lignin extracted from biomass

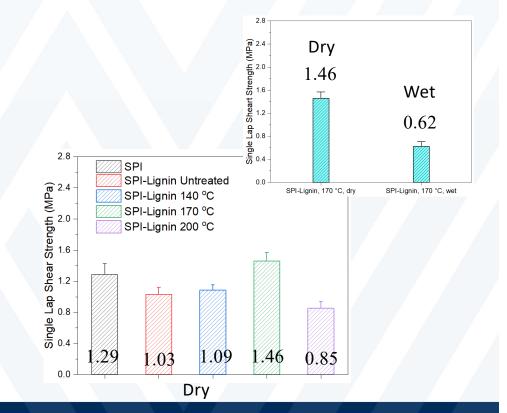


[1] Katahira, Rui, et al. "Base-catalyzed depolymerization of biorefinery lignins." ACS Sustainable Chemistry & Engineering 4.3 (2016): 1474-1486.



Bonding Strength: Single Lap Shear Test

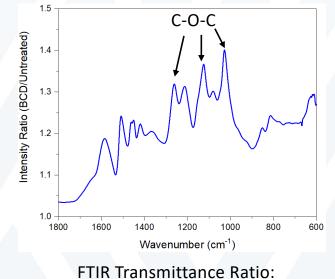
- High lignin loading, ~50 wt.%. Each adhesive was repeated five times for single lap shear strength
- It is speculated that lignin oligomers formed at 170 °C has the best crosslinking performance with soy protein isolate. The resultant adhesive SPI-D-Lignin has a higher strength than SPI adhesive.
- Lignin fragments resulted from higher temperatures might decrease the bonding strength
- Wet strength test: samples were soaked in water for 3 hr at room temperature before test.





FTIR Characterization: Degraded Lignin vs Untreated Lignin

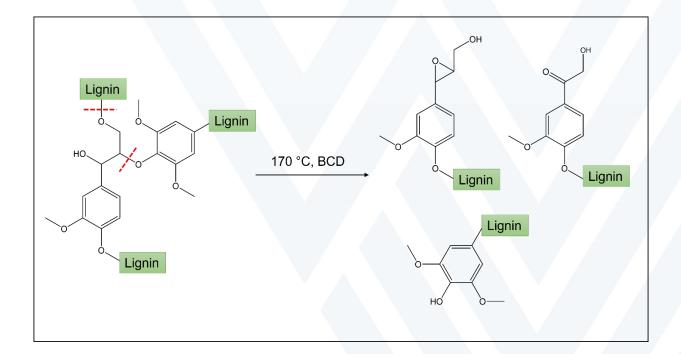
- Transmittance Intensity of C-O-C was visibly changed by observing peaks at 1028, 1214, and 1261 cm⁻¹
- Direct evidence of cleavage of β-O-4 ether taking place during depolymerization.



D-lignin/untreated lignin



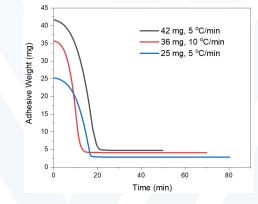
Possible Depolymerization Reactions

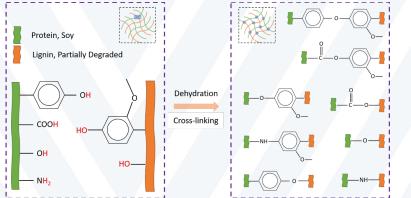




Curing of Adhesive and Possible Reactions

- ✤ Adhesive is observed to be cured within 25 mins.
- ✤ Measured solid contents is ~11.5%.
- Possible curing reactions of adhesive: dehydration (ether or ester) and secondary amine forming reactions.







Future Work

- LC-MS and NMR characterization of depolymerized lignin
- Correlation of viscosity to the bonding strength
- Transition metal catalyzed lignin deconstruction
- Selectivity of lignin depolymerization products

